Surface Mount Fast Recovery Rectifier





Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Fast reverse recovery time
- \bullet Meets MSL level 1, per J-STD-020, LF maximum peak of 260 $^\circ\text{C}$

Typical Applications

For use in high frequency rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, and telecommunication.

Mechanical Data

- Package: SMBF Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- Terminals: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

■Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	GR4MBF
Device marking code			GR4MBF
Maximum Repetitive Peak Reverse Voltage	VRRM	V	1000
Maximum RMS Voltage	VRMS	V	700
Maximum DC blocking Voltage	VDC	V	1000
Average rectified output current @60Hz half-sine wave, resistance load, TC (Fig.1)	lO	A	4.0
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25°C		A	120
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25°C	I _{FSM}		240
Current squared time @1ms≤t≤8.3ms Tj=25℃,Rating of per diode	l²t	A²s	60
Typical junction capacitance @Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	Cj	pF	30
Storage temperature	T _{stg}	°C	-55 ~ +150
Junction temperature	Tj	°C	-55 ~ +150

Electrical Characteristics ($T_a=25^{\circ}C$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	GR4MBF
Maximum instantaneous forward voltage drop per diode	VF	V	IFM=4.0A	1.3
Maximum reverse recovery time	t _{rr}	ns	I _F =0.5A,I _R =1.0A, I _π =0.25A	500
			Т _ј =25°С	5.0
Maximum DC reverse current at rated DC blocking voltage per diode	IR	μA	Tj =125℃	100

Thermal Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	GR4MBF	
	$R_{\theta J-A}^{(1)}$		60	
Typical Thermal resistance	$R_{\theta J-L}^{(1)}$	°C/W	°C/W	20
	$R_{\theta J-C}^{(1)}$		15	

Note:

(1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3" x 0.3" (8.0 mm x 8.0 mm) copper pad areas

Characteristics (Typical)





FIG.5: Diagram of circuit and Testing wave form of reverse recovery time



■Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
GR4MBF	F1	Approximate 0.065	5000	/	80000	13" reel

Outline Dimensions



SMBF		
Dim	Min	Max
А	3.40	3.80
В	1.90	2.10
С	4.15	4.45
D	5.10	5.60
E	1.05	1.55
F	0.70	1.35
G	0.15	0.25

3/5



Suggested pad layout



Dim	Milimeters
P1	6.20
P2	2.40
Q1	1.90
Q2	2.20

GR4MBF

Disclaimer

The information presented in this document is for reference only. Yangzhou Yangjie Electronic Technology Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website http:// www.21yangjie.com , or consult your nearest Yangjie's sales office for further assistance.